

Title (en)  
INDUCTIVE COMPONENT AND METHOD FOR MANUFACTURING AN INDUCTIVE COMPONENT

Title (de)  
INDUKTIVES BAUELEMENT UND VERFAHREN ZUM HERSTELLEN EINES INDUKTIVEN BAUELEMENTS

Title (fr)  
COMPOSANT INDUCTIF ET PROCEDE DE REALISATION D'UN COMPOSANT INDUCTIF

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Application  
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Abstract (en)  
[origin: WO2007131884A1] The invention relates to a method for manufacturing an inductive component that is constructed from multiple layers in which the following steps are performed: a) Arrangement of an electrically conducting material (511 to 514; 521 to 524) as a winding of the component (I, II, III, IV) on a first nonmagnetic dielectric ceramic layer (5; 5a to 5h); b) Construction of at least one continuous recess (53, 53', 53", 53''') in the nonmagnetic dielectric ceramic layer (5, 5a to 5h); c) Arrangement of a first magnetic ceramic layer (6) on an upper side and of a second magnetic ceramic layer (7) on an underside of the nonmagnetic dielectric ceramic layer (5, 5a to 5h); and d) Performing a process step in which at least one of the magnetic ceramic layers (6, 7) is plastically deformed, in such a way that both the magnetic ceramic layers (6, 7) are contacted in the region of the recess (53, 53', 53", 53''') and form a magnetic core of the component (I, II, III, IV). The invention also relates to an inductive element of this type.

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